



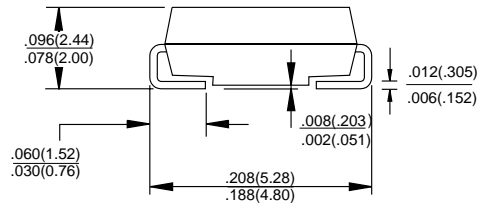
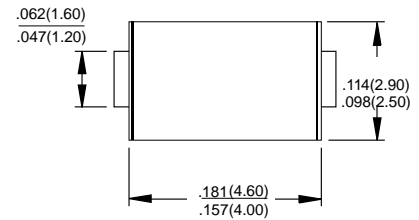
FEATURES

- For surface mounted applications
- Low profile package
- Built-in strain relief
- Easy pick and place
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Low forward drop
- High temperature soldering: 260°C /10 seconds at terminals
- Pb free product at available: 99% Sn above meet RoHS environment substance directive request

MECHANICAL DATA

- Case: JEDEC DO-214AC molded plastic
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Indicated by cathode band
- Standard packaging: 12mm tape (EIA-481)

SMA/DO-214AC Unit:inch(mm)



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

PARAMETER	SYMBOL	GS2A	GS2B	GS2D	GS2G	GS2J	GS2K	GS2M	UNITS
Maximum Recurrent Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current, at TL=75°C	I(AV)	2.0							A
Peak Forward Surge Current 8.3ms single half sine-wave super imposed on rated load (JEDEC method)	IFSM	60.0							A
Maximum Instantaneous Forward Voltage at 2.0A	VF	1.1							V
Maximum DC Reverse Current TA=25°C at Rated DC Blocking Voltage TA=125°C	IR	5.0 100							uA uA
Typical Junction Capacitance (Note 1)	CJ	12							pF
Maximum Thermal Resistance (Note 2)	R θJA	25							°C /W
Operating and Storage Temperature Range	TJ , TSTG	-55 to +150							°C

NOTES:

1. Measured at 1 MHz and applied Vr = 4.0 Volts.
2. 8.0mm² (.013mm thick) land areas.

DEVICE CHARACTERISTICS

GS2A THRU GS2M

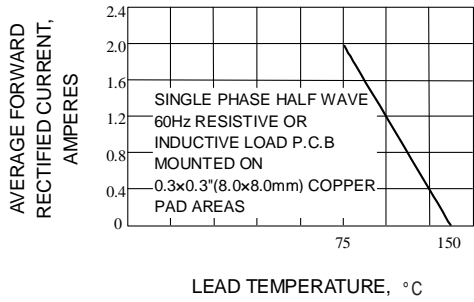


Fig. 1-FORWARD CURRENT DERATING CURVE

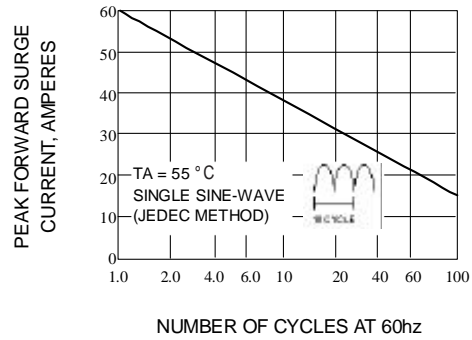


Fig. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

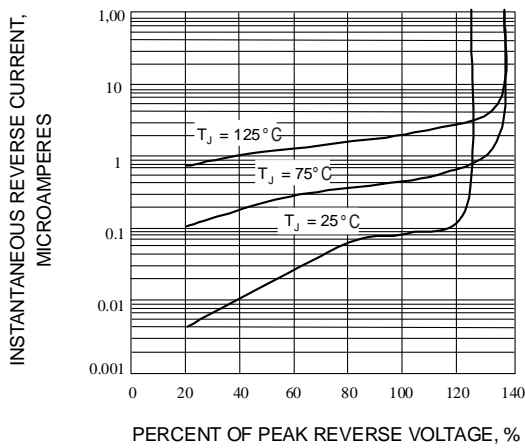


Fig. 3-TYPICAL REVERSE CHARACTERISTICS

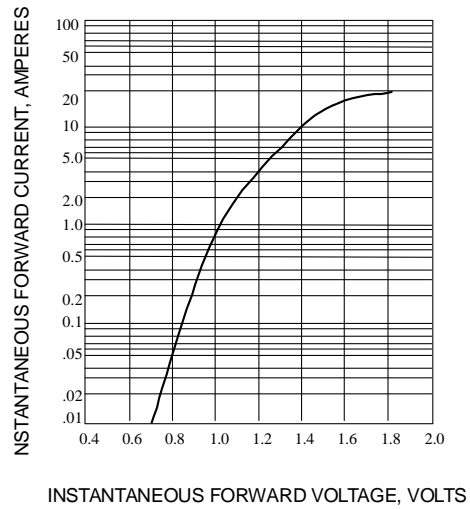


Fig. 4-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

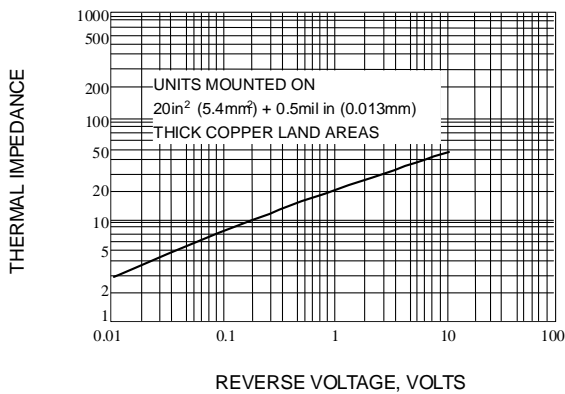


Fig. 5-TRANSIENT THERMAL IMPEDANCE

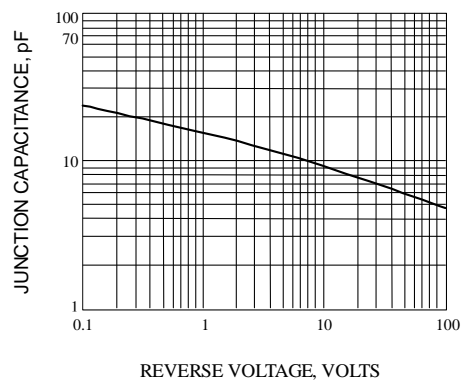


Fig. 6-TYPICAL JUNCTION CAPACITANCE